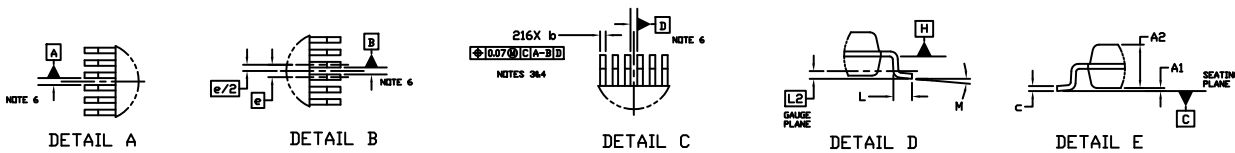
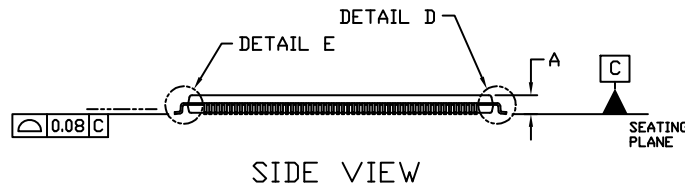
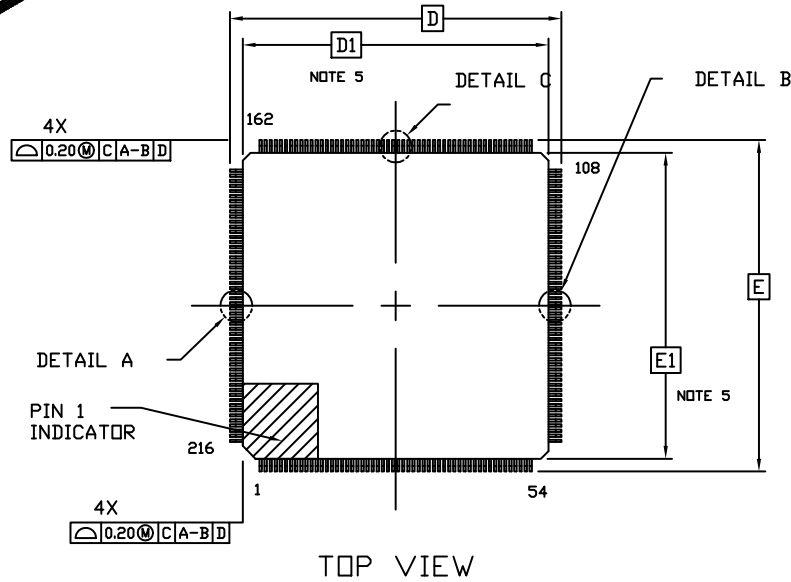
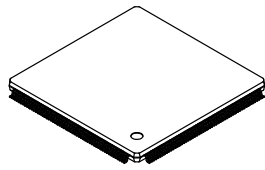


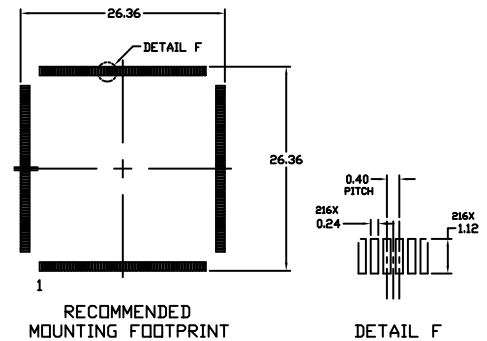
LQFP216 24x24
CASE 561BE
ISSUE O

DATE 23 JUL 2013



- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 - CONTROLLING DIMENSION: MILLIMETERS
 - DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF b AT MMC.
 - DIMENSION b APPLIES TO THE PLATED LEAD AND IS MEASURED BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
 - DIMENSIONS D1 AND E1 ARE DETERMINED AT DATUM PLANE H. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSIONS OR FLASH. MOLD PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE INCLUDING MOLD MISMATCH.
 - DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE LEAD AND IS COINCIDENT WITH WHERE THE LEADS EXIT THE PLASTIC BODY AT THE AT THE BOTTOM OF THE PARTING LINE. DATUMS A, B, AND D ARE TO BE DETERMINED AT DATUM PLANE H.
 - DIMENSIONS D AND E ARE TO BE DETERMINED AT SEATING PLANE DATUM C.
 - EXACT SHAPE OF EACH CORNER IS OPTIONAL.
 - A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.60
A1	0.05	0.15
A2	1.35	1.45
b	0.13	0.23
c	0.09	0.20
D	26.00	BSC
D1	24.00	BSC
E	26.00	BSC
E1	24.00	BSC
e	0.40	BSC
L	0.45	0.75
L2	0.25	BSC
M	0°	7°



DOCUMENT NUMBER:	98AON76115F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	LQFP216 24X24	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.